



Material Content Data Sheet



Sales Product Name	TLE4305G			Issued		28. August 2013		
MA#	MA000981464							
Package	PG-DSO-8-16			Weight*		83.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.141	1.37	1.37	13742	13742
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.717	0.86		8637	
	non noble metal	copper	7440-50-8	29.121	35.07	35.98	350708	359885
wire	noble metal	gold	7440-57-5	0.204	0.25	0.25	2459	2459
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1191	
	plastics	epoxy resin	-	4.549	5.48		54780	
	inorganic material	silicondioxide	60676-86-0	44.795	53.95	59.55	539464	595435
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9801	9801
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7831	7831
glue	plastics	acrylic resin	-	0.198	0.24		2386	
	noble metal	silver	7440-22-4	0.703	0.85	1.09	8461	10847
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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